

树脂刀

Resin Bond Dicing Blades

产品概述：树脂结合剂整体型切割砂轮主要用于半导体封装材料、光学玻璃、石英玻璃、陶瓷材料等精密元器件的精密切割与开槽。

Product overview: Resin bond dicing blades without steel core is mainly used for precision cutting and slotting for semiconductor, optical glass, quartz glass, ceramics and so on.

主要特点：结合剂富有弹性，可提高加工表面质量；切割锋利可有效减少砂轮修整次数或无需修整；切割精度高，适用范围广泛；尺寸规格多样，供货周期短。

Main features: Sharpness cutting and elastic bond can improve the surface quality. High precision, less dressing or no need to dress. Widely used, variety specifications, short delivery time.

主要应用领域：ZS001 系列适用于半导体封装材料（KFN、DFN 等）的加工，有效的防止纵向和横向拉毛，加工效率高，使用寿命长；

ZS002 系列适用于光学玻璃的加工，有效的防止崩口和背崩现象，提高成品率；

ZS003 系列适用于石英玻璃的加工，有效的防止崩口，加工效率高，产品光洁度好；

ZS004 系列适用于陶瓷材料的加工，有效防止崩口和切碎现象，提高加工品质；

其他系列对水晶、磁性材料、硬质合金、各种高硬度难加工金属材料的开槽或切断均具有良好的切割品质。

Application: ZS001 series is suitable for semiconductor components(KFN、DFN), which can avoid burrs, and improve efficiency and life.

ZS002 series is suitable for optical glass, which can avoid chip and improve yield.

ZS003 series is suitable for quartz glass, which can avoid chips and improve efficiency, and finish of product.

ZS004 series is suitable for ceramics, which can avoid chips and cracks, and improve the processing quality.

Other series are suitable for slotting and cutting of crystal, magnetic materials, carbide and some other difficult to cut metal materials with excellent cutting quality.

供参考的典型规格及精度

Model specification and the precision for reference(mm)

T \ D	50-60	60-76.2	77-101.6	102-125	125-153	厚度公差 Thick tolerance
0.06						±0.005
0.1						
0.2						
0.3						
0.4						
0.5						±0.008
1.0						
1.5						
2.0						
H	25.4、31.75、40、52、69.875、88.9、114.3					

注：其他规格可根据用户图纸加工

Note: Other specifications can be produced according to customer's requirement

